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Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	4KB (2K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f4220t-i-pt

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2.0 OSCILLATOR CONFIGURATIONS

2.1 Oscillator Types

The PIC18F2X20 and PIC18F4X20 devices can be operated in ten different oscillator modes. The user can program the Configuration bits, FOSC3:FOSC0, in Configuration Register 1H to select one of these ten modes:

- 1. LP Low-Power Crystal
- 2. XT Crystal/Resonator
- 3. HS High-Speed Crystal/Resonator
- 4. HSPLL High-Speed Crystal/Resonator with PLL Enabled
- 5. RC External Resistor/Capacitor with Fosc/4 Output on RA6
- 6. RCIO External Resistor/Capacitor with I/O on RA6
- 7. INTIO1 Internal Oscillator with Fosc/4 Output on RA6 and I/O on RA7
- 8. INTIO2 Internal Oscillator with I/O on RA6 and RA7
- 9. EC External Clock with Fosc/4 Output
- 10. ECIO External Clock with I/O on RA6

2.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HSPLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 2-1 shows the pin connections.

The oscillator design requires the use of a parallel cut crystal.

Note: Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications.

FIGURE 2-1:

CRYSTAL/CERAMIC RESONATOR OPERATION (XT, LP, HS OR HSPLL CONFIGURATION)



TABLE 2-1:CAPACITOR SELECTION FOR
CERAMIC RESONATORS

٦	Typical Capacitor Values Used:						
Mode	Freq	OSC1	OSC2				
XT	455 kHz	56 pF	56 pF				
	2.0 MHz	47 pF	47 pF				
	4.0 MHz	33 pF	33 pF				
HS	8.0 MHz	27 pF	27 pF				
	16.0 MHz	22 pF	22 pF				

Capacitor values are for design guidance only.

These capacitors were tested with the resonators listed below for basic start-up and operation. **These values are not optimized**.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes on page 20 for additional information.

Resonators Used:			
455 kHz	4.0 MHz		
2.0 MHz	8.0 MHz		
16.0 MHz			



2.7.2 OSCILLATOR TRANSITIONS

The PIC18F2X20/4X20 devices contain circuitry to prevent clocking "glitches" when switching between clock sources. A short pause in the system clock occurs during the clock switch. The length of this pause is between 8 and 9 clock periods of the new clock source. This ensures that the new clock source is stable and that its pulse width will not be less than the shortest pulse width of the two clock sources.

Clock transitions are discussed in greater detail in **Section 3.1.2 "Entering Power-Managed Modes"**.

2.8 Effects of Power-Managed Modes on the Various Clock Sources

When the device executes a SLEEP instruction, the system is switched to one of the power-managed modes, depending on the state of the IDLEN and SCS1:SCS0 bits of the OSCCON register. See Section 3.0 "Power-Managed Modes" for details.

When PRI_IDLE mode is selected, the designated primary oscillator continues to run without interruption. For all other power-managed modes, the oscillator using the OSC1 pin is disabled. The OSC1 pin (and OSC2 pin, if used by the oscillator) will stop oscillating.

In secondary clock modes (SEC_RUN and SEC_IDLE), the Timer1 oscillator is operating and providing the system clock. The Timer1 oscillator may also run in all power-managed modes if required to clock Timer1 or Timer3.

In internal oscillator modes (RC_RUN and RC_IDLE), the internal oscillator block provides the system clock source. The INTRC output can be used directly to provide the system clock and may be enabled to support various special features, regardless of the power-managed mode (see Section 23.2 "Watchdog Timer (WDT)" through Section 23.4 "Fail-Safe Clock Monitor"). The INTOSC output at 8 MHz may be used directly to clock the system or may be divided down first. The INTOSC output is disabled if the system clock is provided directly from the INTRC output. If the Sleep mode is selected, all clock sources are stopped. Since all the transistor switching currents have been stopped, Sleep mode achieves the lowest current consumption of the device (only leakage currents).

Enabling any on-chip feature that will operate during Sleep will increase the current consumed during Sleep. The INTRC is required to support WDT operation. The Timer1 oscillator may be operating to support a Real-Time Clock. Other features may be operating that do not require a system clock source (i.e., MSSP slave, PSP, INTx pins, A/D conversions and others).

2.9 Power-up Delays

Power-up delays are controlled by two timers so that no external Reset circuitry is required for most applications. The delays ensure that the device is kept in Reset until the device power supply is stable under normal circumstances and the primary clock is operating and stable. For additional information on power-up delays, see Section 4.1 "Power-on Reset (POR)" through Section 4.5 "Brown-out Reset (BOR)".

The first timer is the Power-up Timer (PWRT) which provides a fixed delay on power-up (parameter 33, Table 26-10), if enabled, in Configuration Register 2L. The second timer is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable (LP, XT and HS modes). The OST does this by counting 1024 oscillator cycles before allowing the oscillator to clock the device.

When the HSPLL Oscillator mode is selected, the device is kept in Reset for an additional 2 ms, following the HS mode OST delay, so the PLL can lock to the incoming clock frequency.

There is a delay of 5 to 10 $\mu s,$ following POR, while the controller becomes ready to execute instructions. This delay runs concurrently with any other delays. This may be the only delay that occurs when any of the EC, RC or INTIO modes are used as the primary clock source.

OSC Mode	OSC1 Pin	OSC2 Pin
RC, INTIO1	Floating, external resistor should pull high	At logic low (clock/4 output)
RCIO, INTIO2	Floating, external resistor should pull high	Configured as PORTA, bit 6
ECIO	Floating, pulled by external clock	Configured as PORTA, bit 6
EC	Floating, pulled by external clock	At logic low (clock/4 output)
LP, XT, and HS	Feedback inverter disabled at quiescent voltage level	Feedback inverter disabled at quiescent voltage level

TABLE 2-3: OSC1 AND OSC2 PIN STATES IN SLEEP MODE

Note: See Table 4-1 in Section 4.0 "Reset" for time-outs due to Sleep and MCLR Reset.

3.0 POWER-MANAGED MODES

The PIC18F2X20 and PIC18F4X20 devices offer a total of six operating modes for more efficient power management (see Table 3-1). These operating modes provide a variety of options for selective power conservation in applications where resources may be limited (i.e., battery-powered devices).

There are three categories of power-managed modes:

- · Sleep mode
- Idle modes
- Run modes

These categories define which portions of the device are clocked and sometimes, what speed. The Run and Idle modes may use any of the three available clock sources (primary, secondary or INTOSC multiplexer); the Sleep mode does not use a clock source.

The clock switching feature offered in other PIC18 devices (i.e., using the Timer1 oscillator in place of the primary oscillator) and the Sleep mode offered by all PIC[®] devices (where all system clocks are stopped) are both offered in the PIC18F2X20/4X20 devices (SEC_RUN and Sleep modes, respectively). However, additional power-managed modes are available that allow the user greater flexibility in determining what portions of the device are operating. The power-managed modes are event driven; that is, some specific event must occur for the device to enter or (more particularly) exit these operating modes.

For PIC18F2X20/4X20 devices, the power-managed modes are invoked by using the existing SLEEP instruction. All modes exit to PRI_RUN mode when triggered by an interrupt, a Reset, or a WDT time-out (PRI_RUN mode is the normal full-power execution mode; the CPU and peripherals are clocked by the primary oscillator source). In addition, power-managed Run modes may also exit to Sleep mode or their corresponding Idle mode.

3.1 Selecting Power-Managed Modes

Selecting a power-managed mode requires deciding if the CPU is to be clocked or not and selecting a clock source. The IDLEN bit controls CPU clocking while the SC1:SCS0 bits select a clock source. The individual modes, bit settings, clock sources and affected modules are summarized in Table 3-1.

3.1.1 CLOCK SOURCES

The clock source is selected by setting the SCS bits of the OSCCON register. Three clock sources are available for use in power-managed Idle modes: the primary clock (as configured in Configuration Register 1H), the secondary clock (Timer1 oscillator) and the internal oscillator block. The secondary and internal oscillator block sources are available for the power-managed modes (PRI_RUN mode is the normal full-power execution mode; the CPU and peripherals are clocked by the primary oscillator source).

Modo	oscco	ON<7,1:0>	Module Clocking		Available Cleak and Ossillator Source
Mode	IDLEN	SCS1:SCS0	CPU	Peripherals	
Sleep	0	00	Off	Off	None – All clocks are disabled
PRI_RUN	0	00	Clocked	Clocked	Primary – LP, XT, HS, HSPLL, RC, EC, INTRC ⁽¹⁾ . This is the normal full-power execution mode.
SEC_RUN	0	01	Clocked	Clocked	Secondary – Timer1 Oscillator
RC_RUN	0	1x	Clocked	Clocked	Internal Oscillator Block ⁽¹⁾
PRI_IDLE	1	00	Off	Clocked	Primary – LP, XT, HS, HSPLL, RC, EC
SEC_IDLE	1	01	Off	Clocked	Secondary – Timer1 Oscillator
RC_IDLE	1	1x	Off	Clocked	Internal Oscillator Block ⁽¹⁾

TABLE 3-1: POWER-MANAGED MODES

Note 1: Includes INTOSC and INTOSC postscaler, as well as the INTRC source.

5.13 STATUS Register

The STATUS register, shown in Register 5-2, contains the arithmetic status of the ALU. The STATUS register can be the operand for any instruction as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC, C, OV or N bits, then the write to these five bits is disabled. These bits are set or cleared according to the device logic. Therefore, the result of an instruction with the STATUS register as destination may be different than intended. For example, CLRF STATUS will clear the upper three bits and set the Z bit. This leaves the STATUS register as 000u uluu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF, MOVFF and MOVWF instructions are used to alter the STATUS register, because these instructions do not affect the Z, C, DC, OV or N bits in the STATUS register. For other instructions not affecting any Status bits (see Table 24-2).

Note:	The	C and	DC	bits	oper	rate	as	a	borre	wo
	and	digit	bor	wor	bit	res	bec	tive	ely,	in
	subt	raction.								

REGISTER 5-2: STATUS REGISTER

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
_	—	—	Ν	OV	Z	DC ⁽¹⁾	C ⁽²⁾
bit 7							bit 0
Legend:							
R = Read	able bit	W = Writable b	pit	U = Unimple	mented bit, read	l as '0'	
-n = Value	e at POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unk	nown
bit 7-5 bit 4	Unimplemen N: Negative b This bit is use (ALU MSB =	nted: Read as 'o bit ed for signed ari 1).	' thmetic (2's d	complement). I	t indicates whet	her the result v	was negative
	1 = Result wa 0 = Result wa	as negative as positive					
bit 3	OV: Overflow This bit is use which causes 1 = Overflow 0 = No overflo	OV: Overflow bit This bit is used for signed arithmetic (2's complement). It indicates an overflow of the 7-bit magnit which causes the sign bit (bit 7 of the result) to change state. 1 = Overflow occurred for signed arithmetic (in this arithmetic operation)					
bit 2	Z: Zero bit 1 = The resul 0 = The resul	t of an arithmeti t of an arithmeti	c or logic op c or logic op	eration is zero eration is not z	ero		
bit 1	DC: Digit Car For ADDWF, A 1 = A carry-o 0 = No carry-	DC: Digit Carry/Borrow bit ⁽¹⁾ For ADDWF, ADDLW, SUBLW and SUBWF instructions: A carry-out from the 4th low-order bit of the result occurred 					
bit 0	C: Carry/Borrow bit ⁽²⁾ For ADDWF, ADDLW, SUBLW and SUBWF instructions: 1 = A carry-out from the Most Significant bit of the result occurred 0 = No carry-out from the Most Significant bit of the result occurred						
Note 1: 2:	For Borrow, the po operand. For rotate For Borrow, the po operand. For rotate source register.	br Borrow, the polarity is reversed. A subtraction is executed by adding the 2's complement of the second perand. For rotate (RRF, RLF) instructions, this bit is loaded with either bit 4 or bit 3 of the source register Borrow, the polarity is reversed. A subtraction is executed by adding the 2's complement of the second perand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high or low-order bit of the second perand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high or low-order bit of the second perand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high or low-order bit of the second perand.					

6.0 FLASH PROGRAM MEMORY

The Flash program memory is readable, writable and erasable during normal operation over the entire VDD range.

A read from program memory is executed on one byte at a time. A write to program memory is executed on blocks of 8 bytes at a time. Program memory is erased in blocks of 64 bytes at a time. A bulk erase operation may not be issued from user code.

While writing or erasing program memory, instruction fetches cease until the operation is complete. The program memory cannot be accessed during the write or erase, therefore, code cannot execute. An internal programming timer terminates program memory writes and erases.

A value written to program memory does not need to be a valid instruction. Executing a program memory location that forms an invalid instruction results in a NOP.

6.1 Table Reads and Table Writes

In order to read and write program memory, there are two operations that allow the processor to move bytes between the program memory space and the data RAM:

- Table Read (TBLRD)
- Table Write (TBLWT)

The program memory space is 16 bits wide while the data RAM space is 8 bits wide. Table reads and table writes move data between these two memory spaces through an 8-bit register (TABLAT).

Table read operations retrieve data from program memory and place it into TABLAT in the data RAM space. Figure 6-1 shows the operation of a table read with program memory and data RAM.

Table write operations store data from TABLAT in the data memory space into holding registers in program memory. The procedure to write the contents of the holding registers into program memory is detailed in **Section 6.5 "Writing to Flash Program Memory"**. Figure 6-2 shows the operation of a table write with program memory and data RAM.

Table operations work with byte entities. A table block containing data, rather than program instructions, is not required to be word aligned. Therefore, a table block can start and end at any byte address. If a table write is being used to write executable code into program memory, program instructions will need to be word-aligned (TBLPTRL<0> = 0).

The EEPROM on-chip timer controls the write and erase times. The write and erase voltages are generated by an on-chip charge pump rated to operate over the voltage range of the device for byte or word operations.



FIGURE 6-1: TABLE READ OPERATION

NOTES:

15.3 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 or TMR3 registers when an event occurs on pin RC2/CCP1/P1A. An event is defined as one of the following:

- every falling edge
- · every rising edge
- every 4th rising edge
- · every 16th rising edge

The event is selected by control bits, CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit, CCP1IF (PIR1<2>), is set; it must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value is overwritten by the new captured value.

15.3.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1/P1A pin should be configured as an input by setting the TRISC<2> bit.

Note:	If the RC2/CCP1/P1A is configured as an
	output, a write to the port can cause a capture condition.

15.3.2 TIMER1/TIMER3 MODE SELECTION

The timers that are to be used with the capture feature (either Timer1 and/or Timer3) must be running in Timer mode or Synchronized Counter mode. In Asynchronous Counter mode, the capture operation may not work. The timer to be used with each CCP module is selected in the T3CON register.

15.3.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit, CCP1IF, following any such change in operating mode.

15.3.4 CCP PRESCALER

There are four prescaler settings specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore, the first capture may be from a non-zero prescaler. Example 15-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the "false" interrupt.

EXAMPLE 15-1: CHANGING BETWEEN CAPTURE PRESCALERS

CON, F ;	; Turn CCP module off
CAPT_PS ;	; Load WREG with the
;	; new prescaler mode
;	; value and CCP ON
CON ;	; Load CCP1CON with
;	; this value
	CON, F CAPT_PS CON





FIGURE 16-8: PWM DIRECTION CHANGE







Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Valu POR,	ie on , BOR	Valu all c Res	e on other sets
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000	000x	0000	000u
RCON	IPEN	_		RI	TO	PD	POR	BOR	01	11q0	0q	qquu
PIR1	PSPIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000	0000	0000	0000
PIE1	PSPIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000	0000	0000	0000
IPR1	PSPIP	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	1111	1111	1111	1111
TMR2	Timer2 Mod	dule Register							0000	0000	0000	0000
PR2	Timer2 Mod	dule Period R	legister						1111	1111	1111	1111
T2CON	_	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000	0000	-000	0000
TRISC	PORTC Data Direction Register								1111	1111	1111	1111
TRISD	PORTD Data Direction Register								1111	1111	1111	1111
CCPR1H	Enhanced Capture/Compare/PWM Register 1 High Byte :							XXXX	XXXX	uuuu	uuuu	
CCPR1L	Enhanced Capture/Compare/PWM Register 1 Low Byte						XXXX	XXXX	uuuu	uuuu		
CCP1CON	P1M1	P1M0	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	0000	0000	0000	0000
ECCPAS	ECCPASE	ECCPAS2	ECCPAS1	ECCPAS0	PSSAC1	PSSAC0	PSSBD1	PSSBD0	0000	0000	0000	0000
PWM1CON	PRSEN	PDC6	PDC5	PDC4	PDC3	PDC2	PDC1	PDC0	0000	0000	0000	0000
OSCCON	IDLEN	IRCF2	IRCF1	IRCF0	OSTS	IOFS	SCS1	SCS0	0000	q000	0000	q000

TABLE 16-2:	REGISTERS ASSOCIATED WITH ENHANCED PWM AND TIMER2
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Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the ECCP module in enhanced PWM mode.

17.4.2 OPERATION

The MSSP module functions are enabled by setting MSSP Enable bit, SSPEN (SSPCON1<5>).

The SSPCON1 register allows control of the I²C operation. Four mode selection bits (SSPCON1<3:0>) allow one of the following I²C modes to be selected:

- I²C Master mode, clock = Fosc/(4 * (SSPADD + 1))
- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Slave mode (7-bit address), with Start and Stop bit interrupts enabled
- I²C Slave mode (10-bit address), with Start and Stop bit interrupts enabled
- I²C Firmware Controlled Master mode, slave is Idle

Selection of any I²C mode, with the SSPEN bit set, forces the SCL and SDA pins to be open-drain, provided these pins are programmed to inputs by setting the appropriate TRISC bits. To ensure proper operation of the module, pull-up resistors must be provided externally to the SCL and SDA pins.

17.4.3 SLAVE MODE

In Slave mode, the SCL and SDA pins must be configured as inputs (TRISC<4:3> set). The MSSP module will override the input state with the output data when required (slave-transmitter).

The I^2C Slave mode hardware will always generate an interrupt on an address match. Through the mode select bits, the user can also choose to interrupt on Start and Stop bits.

When an address is matched, or the data transfer after an address match is received, the hardware automatically will generate the Acknowledge (\overline{ACK}) pulse and load the SSPBUF register with the received value currently in the SSPSR register.

Any combination of the following conditions will cause the MSSP module not to give this ACK pulse:

- The Buffer Full bit, BF (SSPSTAT<0>), was set before the transfer was received.
- The overflow bit, SSPOV (SSPCON1<6>), was set before the transfer was received.

In this case, the SSPSR register value is not loaded into the SSPBUF but bit SSPIF (PIR1<3>) is set. The BF bit is cleared by reading the SSPBUF register, while bit SSPOV is cleared by software.

The SCL clock input must have a minimum high and low for proper operation. The high and low times of the I^2C specification, as well as the requirement of the MSSP module, are shown in timing parameter #100 and parameter #101.

17.4.3.1 Addressing

Once the MSSP module has been enabled, it waits for a Start condition to occur. Following the Start condition, the 8 bits are shifted into the SSPSR register. All incoming bits are sampled with the rising edge of the clock (SCL) line. The value of register SSPSR<7:1> is compared to the value of the SSPADD register. The address is compared on the falling edge of the eighth clock (SCL) pulse. If the addresses match and the BF and SSPOV bits are clear, the following events occur:

- 1. The SSPSR register value is loaded into the SSPBUF register.
- 2. The Buffer Full bit, BF, is set.
- 3. An ACK pulse is generated.
- 4. MSSP Interrupt Flag bit, SSPIF (PIR1<3>), is set (interrupt is generated if enabled) on the falling edge of the ninth SCL pulse.

In 10-Bit Addressing mode, two address bytes need to be received by the slave. The five Most Significant bits (MSbs) of the first address byte specify if this is a 10-bit address. Bit R/\overline{W} (SSPSTAT<2>) must specify a write so the slave device will receive the second address byte. For a 10-bit address, the first byte would equal '11110 A9 A8 0', where 'A9' and 'A8' are the two MSbs of the address. The sequence of events for 10-bit addressing is as follows, with steps 7 through 9 for the slave-transmitter:

- 1. Receive first (high) byte of address (bits SSPIF, BF and bit UA (SSPSTAT<1>) are set).
- 2. Update the SSPADD register with second (low) byte of Address (clears bit, UA, and releases the SCL line).
- 3. Read the SSPBUF register (clears bit, BF) and clear flag bit, SSPIF.
- 4. Receive second (low) byte of address (bits, SSPIF, BF and UA, are set).
- 5. Update the SSPADD register with the first (high) byte of address. If match releases SCL line, this will clear bit, UA.
- 6. Read the SSPBUF register (clears bit, BF) and clear flag bit, SSPIF.
- 7. Receive Repeated Start condition.
- 8. Receive first (high) byte of address (bits, SSPIF and BF, are set).
- 9. Read the SSPBUF register (clears bit, BF) and clear flag bit, SSPIF.

17.4.7.2 Clock Arbitration

Clock arbitration occurs when the master, during any receive, transmit or Repeated Start/Stop condition, deasserts the SCL pin (SCL allowed to float high). When the SCL pin is allowed to float high, the Baud Rate Generator (BRG) is suspended from counting until the SCL pin is actually sampled high. When the

SCL pin is sampled high, the Baud Rate Generator is reloaded with the contents of SSPADD<6:0> and begins counting. This ensures that the SCL high time will always be at least one BRG rollover count in the event that the clock is held low by an external device (Figure 17-18).





18.2 USART Baud Rate Generator (BRG)

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit Baud Rate Generator. The SPBRG register controls the period of a free-running 8-bit timer. In Asynchronous mode, bit BRGH (TXSTA<2>) also controls the baud rate. In Synchronous mode, bit BRGH is ignored. Table 18-1 shows the formula for computation of the baud rate for different USART modes which only apply in Master mode (internal clock).

Given the desired baud rate and Fosc, the nearest integer value for the SPBRG register can be calculated using the formula in Table 18-1. From this, the error in baud rate can be determined.

Example 18-1 shows the calculation of the baud rate error for the following conditions:

- Fosc = 16 MHz
- Desired Baud Rate = 9600
- BRGH = 0
- SYNC = 0

It may be advantageous to use the high baud rate (BRGH = 1), even for slower baud clocks, because the Fosc/(16 (X + 1)) equation can reduce the baud rate error in some cases.

Writing a new value to the SPBRG register causes the BRG timer to be reset (or cleared). This ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

18.2.1 POWER-MANAGED MODE OPERATION

The system clock is used to generate the desired baud rate; however, when a power-managed mode is entered, the clock source may be operating at a different frequency than in PRI_RUN mode. In Sleep mode, no clocks are present and in PRI_IDLE, the primary clock source continues to provide clocks to the baud rate generator; however, in other power-managed modes, the clock frequency will probably change. This may require the value in SPBRG to be adjusted.

18.2.2 SAMPLING

The data on the RC7/RX/DT pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin.

EXAMPLE 18-1: CALCULATING BAUD RATE ERROR

Desired Baud Rate	= Fosc/(64 (X + 1))
Solving for X:	
Х	= $((FOSC/Desired Baud Rate)/64) - 1$
Х	= ((1600000/9600)/64) - 1
Х	= [25.042] = 25
Calculated Baud Rate	$e = \frac{16000000}{(64(25+1))} = \frac{9615}{}$
Error	= (Calculated Baud Rate – Desired Baud Rate)
Desired Baud Rate	
	= (9615 - 9600)/9600
	= 0.16%

TABLE 18-1: BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0 (Asynchronous)	Baud Rate = Fosc/(64 (X + 1))	Baud Rate = Fosc/(16 (X + 1))
1 (Synchronous)	Baud Rate = Fosc/(4 (X + 1))	N/A

Legend: X = value in SPBRG (0 to 255)

TABLE 18-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
SPBRG Baud Rate Generator Register								0000 0000	0000 0000
	Bit 7 CSRC SPEN Baud Rat	Bit 7 Bit 6 CSRC TX9 SPEN RX9 Baud Rate Genera	Bit 7Bit 6Bit 5CSRCTX9TXENSPENRX9SRENBaud Rate Generator Registrements	Bit 7Bit 6Bit 5Bit 4CSRCTX9TXENSYNCSPENRX9SRENCRENBaud Rate Generator Register	Bit 7Bit 6Bit 5Bit 4Bit 3CSRCTX9TXENSYNC—SPENRX9SRENCRENADDENBaud Rate Generator Register	Bit 7Bit 6Bit 5Bit 4Bit 3Bit 2CSRCTX9TXENSYNC—BRGHSPENRX9SRENCRENADDENFERRBaud Rate Generator Register	Bit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1CSRCTX9TXENSYNC—BRGHTRMTSPENRX9SRENCRENADDENFERROERRBaud Rate Generator Register	Bit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1Bit 0CSRCTX9TXENSYNC—BRGHTRMTTX9DSPENRX9SRENCRENADDENFERROERRRX9DBaud Rate Generator Register	Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 Value on POR, BOR CSRC TX9 TXEN SYNC — BRGH TRMT TX9D 0000 -010 SPEN RX9 SREN CREN ADDEN FERR OERR RX9D 0000 000x Baud Rate Generator Register Image: Constraint of the second of the seco

Legend: x = unknown, - = unimplemented, read as '0'. Shaded cells are not used by the BRG.

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (AVDD and AVss), or the voltage level on the RA3/AN3/ VREF+ and RA2/AN2/VREF-/CVREF pins.

The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in SLEEP, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the converter which generates the result via successive approximation.



FIGURE 19-1: A/D BLOCK DIAGRAM

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D converter can be configured as an analog input or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH/ADRESL registers, the GO/DONE bit (ADCON0 register) is cleared and A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 19-1.

U-0	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
			WDTPS3	WDTPS2	WDTPS1	WDTPS0	WDTEN
bit 7							bit 0
Legend:							
R = Readable	bit	P = Program	nable bit	U = Unimpler	mented bit, read	as '0'	
-n = Value whe	en device is unp	programmed		u = Unchang	ed from progran	nmed state	
bit 7-5	Unimplemen	ted: Read as '	0'				
bit 4-1	WDPS<3:0>:	Watchdog Tim	er Postscale	Select bits			
	1111 = 1:32. 7	768					
	1110 = 1:16,3	384					
	1101 = 1:8,19	92					
	1100 = 1:4,09	96					
	1011 = 1:2,0 4	48					
	1010 = 1:1,02	24					
	1001 = 1:512						
	1000 = 1:256						
	0111 = 1:128						
	0110 = 1:64						
	0101 = 1:32						
	0100 = 1:16						
	0011 = 1:8						
	0010 = 1:4						
	0001 = 1:2						
	0000 = 1.1						
bit 0	WDTEN: Wat	chdog Timer E	nable bit				
	1 = WDT ena	bled					
	0 = WDT disa	abled (control is	s placed on the	e SWDTEN bit)		

REGISTER 23-3: CONFIG2H: CONFIGURATION REGISTER 2 HIGH (BYTE ADDRESS 300003h)

REGISTER 23-6: CONFIG5L: CONFIGURATION REGISTER 5 LOW (BYTE ADDRESS 300008h)

U-0	U-0	U-0	U-0	R/C-1	R/C-1	R/C-1	R/C-1	
—	—	—	—	CP3 ⁽¹⁾	CP2 ⁽¹⁾	CP1	CP0	
bit 7							bit 0	
Legend:								
R = Readable	bit	C = Clearable	bit	U = Unimpler	mented bit, read	as '0'		
-n = Value whe	en device is unp	programmed		u = Unchang	ed from program	nmed state		
bit 7-4	Unimplemen	ted: Read as ') '					
bit 3	CP3: Code Pr	rotection bit ⁽¹⁾						
	1 = Block 3 (0	01800-001FFF	h) not code-p	orotected				
	0 = Block 3 (0	01800-001FFF	h) code-prote	ected				
bit 2	CP2: Code Pr	rotection bit ⁽¹⁾						
	1 = Block 2 (0	01000-0017FF	h) not code-p	rotected				
	0 = Block 2 (0)	01000-0017FF	h) code-prote	ected				
bit 1	CP1: Code P	rotection bit						
	1 = Block 1 (000800-000FFFh) not code-protected							
	0 = Block 1 (000800-000FFFh) code-protected							
bit 0	bit 0 CP0: Code Protection bit							
	1 = Block 0 (0	00200-0007FF	h) not code-p	rotected				
	0 = Block 0 (000200-0007FFh) code-protected							

Note 1: Unimplemented in PIC18FX220 devices; maintain this bit set.

REGISTER 23-7: CONFIG5H: CONFIGURATION REGISTER 5 HIGH (BYTE ADDRESS 300009h)

R/C-1	R/C-1	U-0	U-0	U-0	U-0	U-0	U-0
CPD	СРВ	—	—	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7	CPD: Data EEPROM Code Protection bit
	1 = Data EEPROM is not code-protected
	0 = Data EEPROM is code-protected
bit 6	CPB: Boot Block Code Protection bit
	1 = Boot block (000000-0001FFh) is not code-protected
	0 = Boot block (000000-0001FFh) is code-protected
bit 5-0	Unimplemented: Read as '0'

23.3 Two-Speed Start-up

The Two-Speed Start-up feature helps to minimize the latency period from oscillator start-up to code execution by allowing the microcontroller to use the INTRC oscillator as a clock source until the primary clock source is available. It is enabled by setting the IESO bit in Configuration Register 1H (CONFIG1H<7>).

Two-Speed Start-up is available only if the primary oscillator mode is LP, XT, HS or HSPLL (Crystal-Based modes). Other sources do not require a OST start-up delay; for these, Two-Speed Start-up is disabled.

When enabled, Resets and wake-ups from Sleep mode cause the device to configure itself to run from the internal oscillator block as the clock source, following the time-out of the Power-up Timer after a POR Reset is enabled. This allows almost immediate code execution while the primary oscillator starts and the OST is running. Once the OST times out, the device automatically switches to PRI_RUN mode.

Because the OSCCON register is cleared on Reset events, the INTOSC (or postscaler) clock source is not initially available after a Reset event; the INTRC clock is used directly at its base frequency. To use a higher clock speed on wake-up, the INTOSC or postscaler clock sources can be selected to provide a higher clock speed by setting bits IFRC2:IFRC0 immediately after Reset. For wake-ups from Sleep, the INTOSC or postscaler clock sources can be selected by setting IFRC2:IFRC0 prior to entering Sleep mode.

In all other power-managed modes, Two-Speed Start-up is not used. The device will be clocked by the currently selected clock source until the primary clock source becomes available. The setting of the IESO bit is ignored.

23.3.1 SPECIAL CONSIDERATIONS FOR USING TWO-SPEED START-UP

While using the INTRC oscillator in Two-Speed Start-up, the device still obeys the normal command sequences for entering power-managed modes, including serial SLEEP instructions (refer to **Section 3.1.3 "Multiple Sleep Commands"**). In practice, this means that user code can change the SCS1:SCS0 bit settings and issue SLEEP commands before the OST times out. This would allow an application to briefly wake-up, perform routine "housekeeping" tasks and return to Sleep before the device starts to operate from the primary oscillator.

User code can also check if the primary clock source is currently providing the system clocking by checking the status of the OSTS bit (OSCCON<3>). If the bit is set, the primary oscillator is providing the system clock. Otherwise, the internal oscillator block is providing the clock during wake-up from Reset or Sleep mode.



ΒZ		Branch if	Branch if Zero				
Synt	ax:	[<i>label</i>] B	Zn				
Оре	rands:	-128 ≤ n ≤	127				
Ope	ration:	if Zero bit (PC) + 2 +	is '1', · 2n \rightarrow F	ъС			
Statu	us Affected:	None					
Enco	oding:	1110	0000	nnr	ın	nnnn	
Deso	cription:	If the Zero program w The 2's co added to t have incre instruction PC + 2 + 2 then a two	If the Zero bit is '1', then the program will branch. The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a two-cycle instruction				
Wor	ds:	1					
Cycl	es:	1(2)					
Q C If Ju	cycle Activity:						
	Q1	Q2	Q3			Q4	
	Decode	Read literal 'n'	Process Data		Wri	te to PC	
	No	No	No			No	
IF NI	operation	operation	operation		ор	eration	
	O Jump. Q1	02	03			Q4	
	Decode	Read literal 'n'	Proce	SS 1	ор	No eration	
Exar	<u>mple</u> : Before Instru	HERE	BZ	Jump			
	PC	= ad	dress (F	HERE)			
	After Instruct If Zero PC If Zero PC	tion = 1; = ad = 0; = ad	dress (C dress (F	Jump) HERE	+ 2)	

CALL		Subrou	Subroutine Call				
Synta	x:	[label]	CALL I	< [,S]			
Opera	ands:	0 ≤ k ≤ ′ s ∈ [0,1]	$0 \le k \le 1048575$ s \in [0,1]				
Opera	ation:	(PC) + 4 $k \rightarrow PC$ if $s = 1$, $(W) \rightarrow W$ (STATU) (BSR) -	- → TOS, <20:1>; VS, S) → STA → BSRS	TUSS	б,		
Status	Affected:	None					
Encoo 1st wo 2nd w	ding: ord (k<7:0> vord(k<19:8) 1110 >) 1111	110s k ₁₉ kkk	k ₇ kl kkk	kk kkkk ₀ :k kkkk ₈		
Descr	iption:	Subrout memory address the return STATUS also pus shadow and BSF occurs (value 'k' CALL is	registers (PC + 4 rn stack. I and BSF shed into registers RS. If 's' = default). is loaded a two-cyd	r entire irst, re) is pu f 's' = R regis their r , WS, , WS, = 0, no Then, J into I cle ins	e 2 Mbyte eturn Ished onto 1, the W, sters are espective STATUSS D update the 20-bit PC<20:1>. truction.		
Words	3:	2					
Cycle	s:	2					
Q Cy	cle Activity:						
	Q1	Q2	Q	3	Q4		
	Decode	Read litera 'k'<7:0>,	I Push P stac	PC to k	Read literal 'k'<19:8>, Write to PC		
	No	No	No	tion	No		
	operation	operation	opera	uon	operation		
Exam	<u>ple</u> :	HERE	CALL	THEF	RE,FAST		
В	efore Instru	iction					
_	PC	= addre	SS (HERE	2)			
A	Iter Instruct PC TOS WS BSRS STATUS	tion = addre = addre = W = BSR S= STAT	ess (Thef ess (here US	RE) 2 + 4)			

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging







	Units	MILLIMETERS			
Dimensior	n Limits	MIN	NOM	MAX	
Number of Pins	N		44	•	
Pitch	е		0.65 BSC		
Overall Height	A	0.80	0.90	1.00	
Standoff	A1	0.00	0.02	0.05	
Contact Thickness	A3		0.20 REF		
Overall Width	E	8.00 BSC			
Exposed Pad Width	E2	6.30	6.45	6.80	
Overall Length	D		8.00 BSC		
Exposed Pad Length	D2	6.30	6.45	6.80	
Contact Width	b	0.25	0.30	0.38	
Contact Length	L	0.30	0.40	0.50	
Contact-to-Exposed Pad	K	0.20	-	_	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated.

- 3. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

PIC18F2220/2320/4220/4320 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	- <u>X</u>	<u>/xx</u>	<u>xxx</u>	Examples:
Device	Temperature Range	Package	Pattern	 a) PIC18LF4320-I/P 301 = Industrial temp., PDIP package, Extended VDD limits, QTP pattern #301. b) PIC18LE2220-I/SO = Industrial temp.
Device	PIC18F2220/2320/4220/4 PIC18F2220/2320/4220/4 VDD range 4.2V to 5 PIC18LF2220/2320/4220/ PIC18LF2220/2320/4220/ VDD range 2.0V to 5	320 ⁽¹⁾ 320T ^(1,2) ; .5V (4320 ⁽¹⁾ , (4320T ^(1,2) ; .5V		 SOIC package, Extended VDD limits. PIC18F4220-I/P = Industrial temp., PDIP package, normal VDD limits.
Temperature Range	$I = -40^{\circ}C \text{ to } +85^{\circ}C$	(Industrial)		Note 1: F = Standard Voltage Range LF = Wide Voltage Range
Package	PT = TQFP (Thin Qua SO = SOIC SP = Skinny Plastic D P = PDIP ML = QFN	ld Flatpack) IP		2: T = in tape and reel – SOIC and TQFP packages only.
Pattern	QTP, SQTP, Code or Spe (blank otherwise)	cial Requiremo	ents	